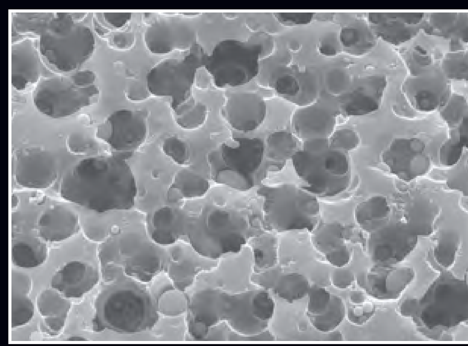
Advanced Desmear / Electroless Copper for Semi-Additive Process | 应用于半加成制程之先进除胶渣及化学沉铜技术

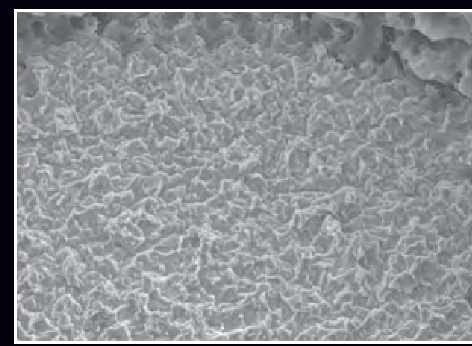
CIRCUPOSIT™ 7800 Desmear Process and CIRCUPOSIT™ 7900 Electroless Copper Process

Features and Benefits 特长及优点

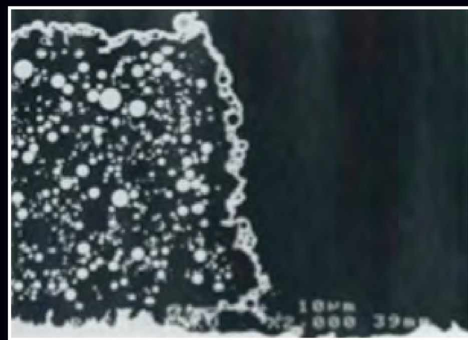
- Uniform and stable adhesion promotion treatment and reliable via bottom cleaning
  能提升均匀且稳定的表面结合能力及对于盲孔孔底有可靠的清洁能力
- Stable and wide process window
  操作范围大且表现稳定
- High peel strength and optimum surface roughness for insulator adhesion
  在绝缘层的贴合表面生成最理想的粗糙度
- Excellent plating coverage of electroless copper on insulator, especially at the bottom of vias
  优越的镀层覆盖能力，使化学沉铜均匀地覆盖在绝缘层表面及盲孔底部
- Excellent electrical reliability with exceptional insulation resistance
  拥有优异的高度绝缘阻抗电性
- Provides great foundation for fine line solution
  为细线路解决方案提供最佳基础



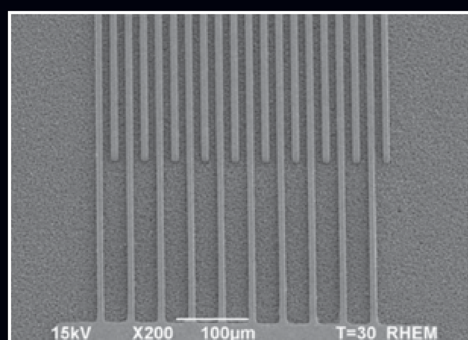
Adhesion promotion on insulator
绝缘层表面的理想粗糙度

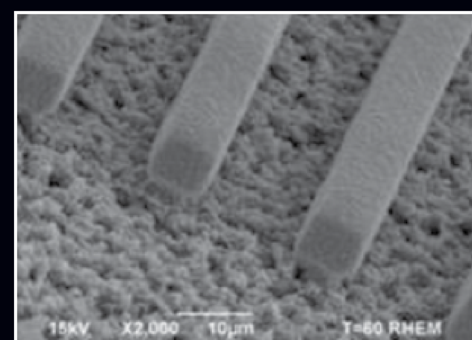


Via bottom cleaning
清洁的盲孔底部



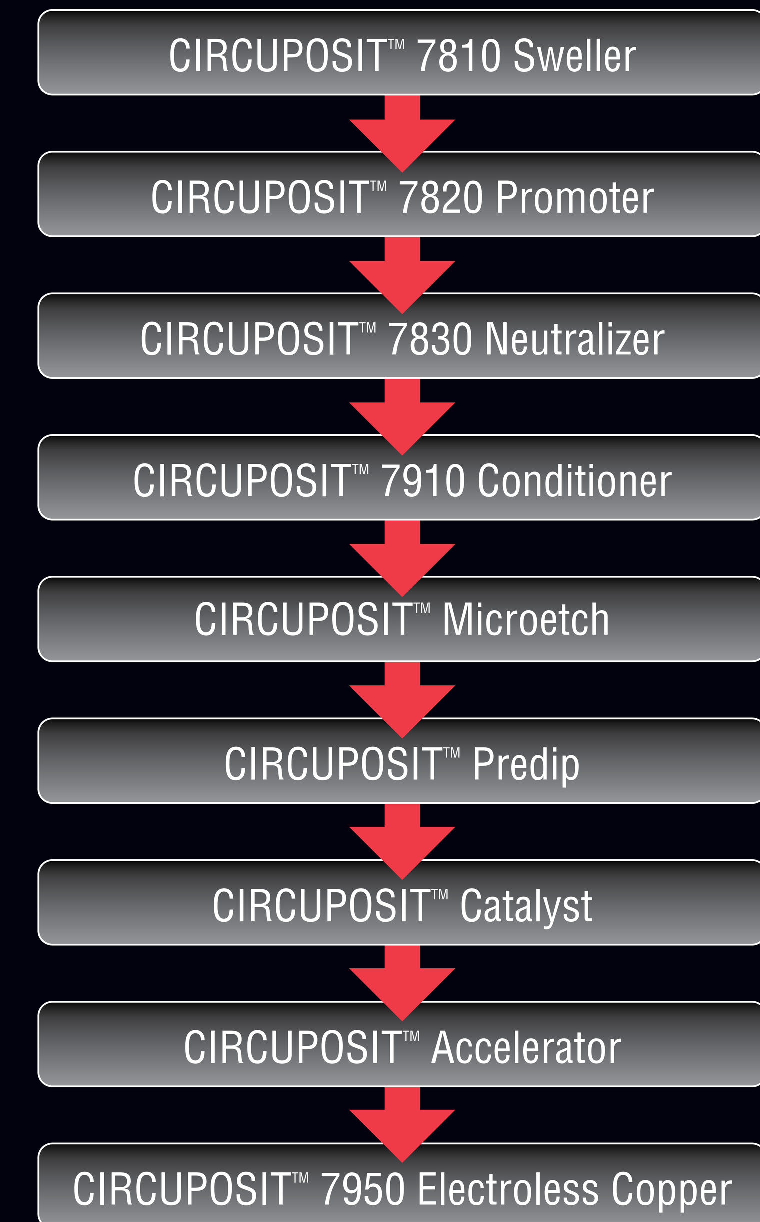
Excellent plating coverage on insulator and via bottom
优越的镀层覆盖能力，使化学沉铜均匀地覆盖在绝缘层表面及盲孔底部

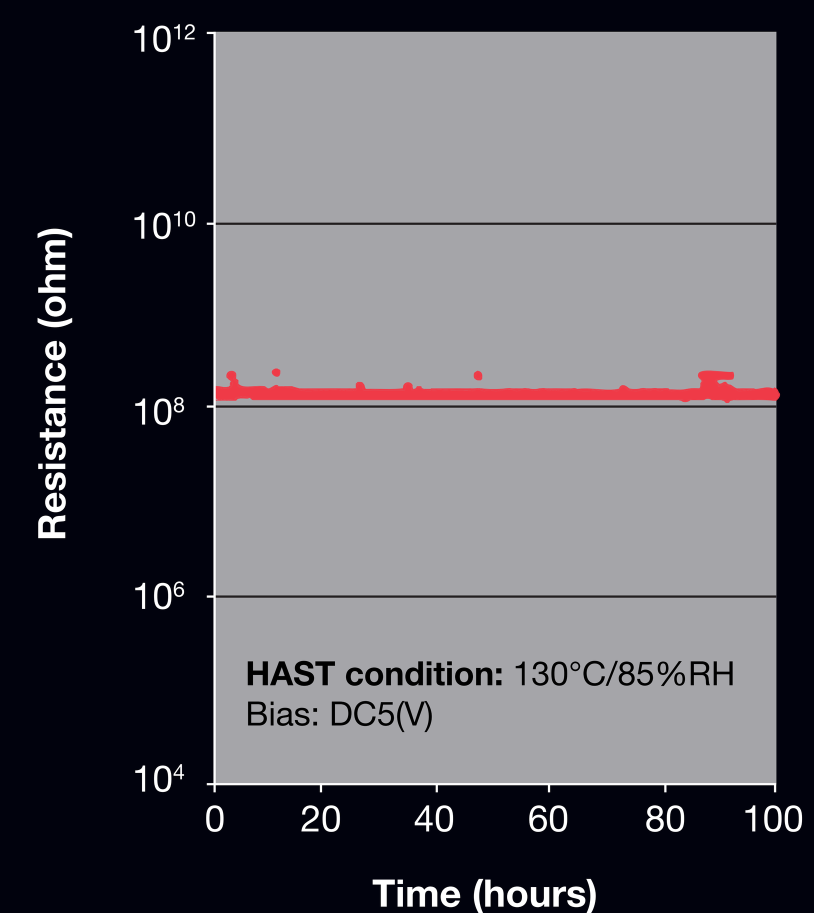




Fine line capability (L/S = 10/10 μm ultra fine line of ABF GX13)
细线路制程能力 (L/S = 10/10 μm 于ABF GX13上之极细线路)

Process 流程





Excellent reliability performance (by migration test on 10/10 μm test vehicle)
拥有优异的高度绝缘阻抗电性

Form No. 886-01649
® ™ Trademarks of The Dow Chemical Company ("Dow") or an affiliated company of Dow